# DATA SHEET

## **89C51/89C52/89C54/89C58** 80C51 8-bit microcontroller family 4K/8K/16K/32K Flash

Product specification

1999 Oct 27

Replaces Datasheets 89C51 of 1999 Apr 01 and 89C52/89C54/89C58 of 1999 Apr 01







Philips Semiconductors Product specification

## 80C51 8-bit microcontroller family 4K/8K/16K/32K Flash

### 89C51/89C52/89C54/89C58

#### **DESCRIPTION**

The 89C51/89C52/89C54/89C58 contain a non-volatile FLASH program memory that is parallel programmable. For devices that are serial programmable (In System Programmable (ISP) with a boot loader), see the 89C51RC+/89C51RD+ datasheet.

Both families are Single-Chip 8-bit Microcontrollers manufactured in advanced CMOS process and are derivatives of the 80C51 microcontroller family. All the devices have the same instruction set as the 80C51.

#### SELECTION TABLE FOR FLASH DEVICES

ROM/EPROM Memory Size (X by 8)	RAM Size (X by 8)	Programmable Timer Counter (PCA)	Hardware Watchdog Timer					
Multi-Time Progr	Multi-Time Programmable (MTP) devices:							
89C51								
4 k	128	No	No					
89C52/54/58								
8 k/16 k/32 k	256	No	No					
Serial In-System	Programmab	le devices:						
89C51RC+								
32 k	32 k 512		Yes					
89C51RD+								
64 k	1024	Yes	Yes					

#### **FEATURES**

- 80C51 Central Processing Unit
- On-chip FLASH Program Memory
- Speed up to 33 MHz
- Full static operation
- RAM expandable externally to 64 k bytes
- 4 level priority interrupt
- 6 interrupt sources
- Four 8-bit I/O ports
- Full-duplex enhanced UART
  - Framing error detection
  - Automatic address recognition
- Power control modes
  - Clock can be stopped and resumed
  - Idle mode
  - Power down mode
- Programmable clock out
- Second DPTR register
- Asynchronous port reset
- Low EMI (inhibit ALE)
- 3 16-bit timers
- Wake up from power down by an external interrupt

#### **ORDERING INFORMATION**

	MEMORY SIZE 4 k × 8	MEMORY SIZE 8 k × 8	MEMORY SIZE 16 k × 8	MEMORY SIZE 32 k × 8	TEMPERATURE RANGE °C AND PACKAGE	VOLTAGE RANGE	FREQ. (MHz)	DWG. #
FLASH	P89C51UBA A	P89C52UBA A	P89C54UBA A	P89C58UBA A	0 to +70, Plastic Leaded Chip Carrier	5 V	0 to 33	SOT187-2
FLASH	P89C51UBP N	P89C52UBP N	P89C54UBP N	P89C58UBP N	0 to +70, Plastic Dual In-line Package	5 V	0 to 33	SOT129-1
FLASH	P89C51UBB B	P89C52UBB B	P89C54UBB B	P89C58UBB B	0 to +70, Plastic Quad Flat Pack	5 V	0 to 33	QFP44 <sup>2</sup>
FLASH	P89C51UFA A	P89C52UFA A	P89C54UFA A	P89C58UFA A <sup>1</sup>	-40 to +85, Plastic Leaded Chip Carrier	5 V	0 to 33	SOT187-2
FLASH	P89C51UFP N	P89C52UFP N	P89C54UFP N	P89C58UFP N <sup>1</sup>	-40 to +85, Plastic Dual In-line Package	5 V	0 to 33	SOT129-1
FLASH	P89C51UFB B	P89C52UFB B	P89C54UFB B	P89C58UFB B <sup>1</sup>	–40 to +85, Plastic Quad Flat Pack	5 V	0 to 33	QFP44 <sup>2</sup>

#### NOTES

- 1. Contact Philips Sales for availability.
- 2. SOT not assigned for this package outline.

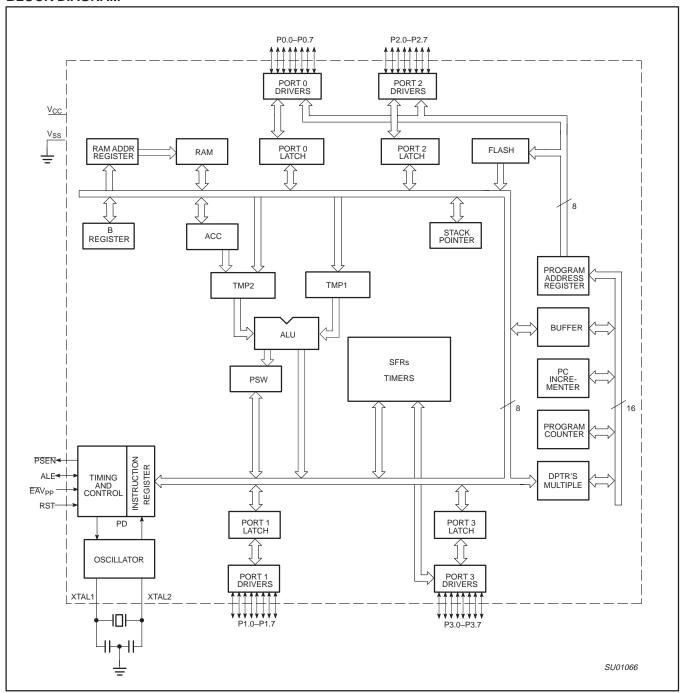
#### PART NUMBER DERIVATION

DEVICE NUMBER (P89CXX)	OPERATING FREQUENCY, MAX (V)	TEMPERATURE RANGE (B)	PACKAGE (AA, BB, PN)
P89C51 FLASH			AA = PLCC
P89C52 FLASH	U = 33 MHz	B = 0°C to 70°C	BB = PQFP
P89C54 FLASH	0 = 33 IVITZ	F = -40°C to 85°C	PN = PDIP
DROCER EL VOH			
~ 00			

2



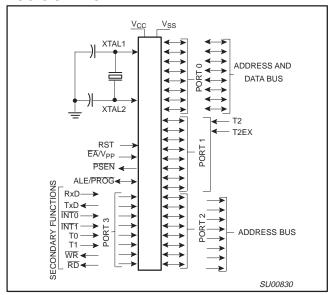
#### **BLOCK DIAGRAM**





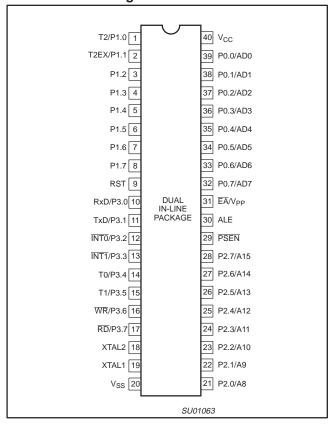
### 89C51/89C52/89C54/89C58

#### LOGIC SYMBOL

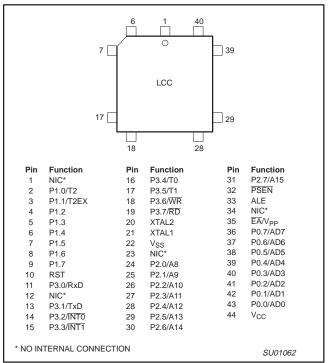


#### **PIN CONFIGURATIONS**

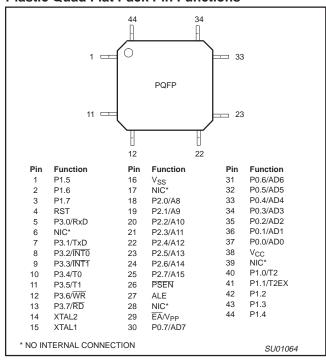
#### **Dual In-Line Package Pin Functions**



## **Ceramic and Plastic Leaded Chip Carrier Pin Functions**



#### **Plastic Quad Flat Pack Pin Functions**





## 89C51/89C52/89C54/89C58

### **PIN DESCRIPTIONS**

PIN DESCR		N NUMB	ER			
MNEMONIC	DIP	LCC	QFP	TYPE	NAME AND FUNCTION	
V <sub>SS</sub>	20	22	16	ı	Ground: 0 V reference.	
V <sub>CC</sub>	40	44	38	1	<b>Power Supply:</b> This is the power supply voltage for normal, idle, and power-down operation.	
P0.0–0.7	39–32	43–36	37–30	I/O	Port 0: Port 0 is an open-drain, bidirectional I/O port. Port 0 pins that have 1s written to them float and can be used as high-impedance inputs. Port 0 is also the multiplexed low-order address and data bus during accesses to external program and data memory. In this application, it uses strong internal pull-ups when emitting 1s.	
P1.0-P1.7	1–8	2–9	40–44, 1–3	I/O	<b>Port 1:</b> Port 1 is an 8-bit bidirectional I/O port with internal pull-ups. Port 1 pins that have written to them are pulled high by the internal pull-ups and can be used as inputs. As inputed 1 pins that are externally pulled low will source current because of the internal pull-up (See DC Electrical Characteristics: I <sub>IL</sub> ). Alternate function for Port 1:	
	1 2	2 3	40 41	I/O I	T2 (P1.0): Timer/Counter2 external count input/clockout (see Programmable Clock-Out).  T2EX (P1.1): Timer/Counter2 reload/capture/direction control.	
P2.0-P2.7	21–28	24–31	18–25	I/O	Port 2: Port 2 is an 8-bit bidirectional I/O port with internal pull-ups. Port 2 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 2 pins that are externally being pulled low will source current because of the internal pull-ups. (See DC Electrical Characteristics: I <sub>IL</sub> ). Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @DPTR). In this application, it uses strong internal pull-ups when emitting 1s. During accesses to external data memory that use 8-bit addresses (MOV @Ri), port 2 emits the contents of the P2 special function register.	
P3.0-P3.7	10–17	11, 13–19	5, 7–13	I/O	Port 3: Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. Port 3 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 3 pins that are externally being pulled low will source current because of the pull-ups. (See DC Electrical Characteristics: I <sub>IL</sub> ). Port 3 also serves the special features of the 89C51/89C52/89C54/89C58, as listed below:	
	10	11	5	ı	RxD (P3.0): Serial input port	
	11	13	7	0	TxD (P3.1): Serial output port	
	12	14	8	I	INTO (P3.2): External interrupt	
	13	15	9	!	NT1 (P3.3): External interrupt	
	14	16 17	10 11		T0 (P3.4): Timer 0 external input T1 (P3.5): Timer 1 external input	
	15 16	18	12	0	WR (P3.6): External data memory write strobe	
	17	19	13	0	RD (P3.7): External data memory read strobe	
RST	9	10	4	I	<b>Reset:</b> A high on this pin for two machine cycles while the oscillator is running, resets the device. An internal diffused resistor to V <sub>SS</sub> permits a power-on reset using only an external capacitor to V <sub>CC</sub> .	
ALE	30	33	27	0	Address Latch Enable: Output pulse for latching the low byte of the address during an access to external memory. In normal operation, ALE is emitted at a constant rate of 1/6 the oscillator frequency, and can be used for external timing or clocking. Note that one ALE pulse is skipped during each access to external data memory. ALE can be disabled by setting SFR auxiliary.0. With this bit set, ALE will be active only during a MOVX instruction.	
PSEN	29	32	26	0	Program Store Enable: The read strobe to external program memory. When executing code from the external program memory, PSEN is activated twice each machine cycle, except that two PSEN activations are skipped during each access to external data memory. PSEN is not activated during fetches from internal program memory.	
EA/V <sub>PP</sub>	31	35	29	I	External Access Enable/Programming Supply Voltage: EA must be externally held low to enable the device to fetch code from external program memory locations 0000H to the maximum internal memory boundary. If EA is held high, the device executes from internal program memory unless the program counter contains an address greater than 0FFFH for 4 k devices, 1FFFH for 8 k devices, 3FFFH for 16 k devices, and 7FFFH for 32 k devices. The value on the EA pin is latched when RST is released and any subsequent changes have no effect. This pin also receives the 12.00 V programming supply voltage (V <sub>PP</sub> ) during FLASH programming.	
XTAL1	19	21	15	I	Crystal 1: Input to the inverting oscillator amplifier and input to the internal clock generator circuits.	
XTAL2	18	20	14	0	Crystal 2: Output from the inverting oscillator amplifier.	



ect at power-on, the voltage on any pin (other than  $V_{PP}$ ) at any time must not be higher than  $V_{CC}$  + 0.5 V or

89C51/89C52/89C54/89C58 Special Function Registers Table 1.

SYMBOL	DESCRIPTION	DIRECT ADDRESS	BIT MSB	ADDRES	SS, SYMB	OL, OR A	LTERNAT	IVE POR	T FUNCT	TON LSB	RESET VALUE
ACC*	Accumulator	E0H	E7	E6	E5	E4	E3	E2	E1	E0	00H
AUXR#	Auxiliary	8EH	-	-	_	-	<u> </u>	-	-	AO	xxxxxxxx0B
AUXR1#	Auxiliary 1	A2H	-	-	-	-	GF2	0	-	DPS	xxxx00x0B
B*	B register	F0H	F7	F6	F5	F4	F3	F2	F1	F0	00H
DPTR: DPH DPL	Data Pointer (2 bytes) Data Pointer High Data Pointer Low	83H 82H									00H 00H
			AF	AE	AD	AC	AB	AA	A9	A8	
IE*	Interrupt Enable	A8H	EA	-	ET2	ES	ET1	EX1	ET0	EX0	0x000000B
			BF	BE	BD	BC	BB	BA	B9	B8	
IP*	Interrupt Priority	B8H	-	-	PT2	PS	PT1	PX1	PT0	PX0	xx000000B
			B7	B6	B5	B4	B3	B2	B1	B0	
IPH#	Interrupt Priority High	B7H	-	_	PT2H	PSH	PT1H	PX1H	PT0H	PX0H	xx000000B
			87	86	85	84	83	82	81	80	
P0*	Port 0	80H	AD7	AD6	AD5	AD4	AD3	AD2	AD1	AD0	FFH
			97	96	95	94	93	92	91	90	
P1*	Port 1	90H	_	_	-	_	_	_	T2EX	T2	FFH
			A7	A6	A5	A4	А3	A2	A1	A0	
P2*	Port 2	A0H	AD15	AD14	AD13	AD12	AD11	AD10	AD9	AD8	FFH
			B7	B6	B5	B4	В3	B2	B1	В0	
P3*	Port 3	B0H	RD	WR	T1	T0	ĪNT1	ĪNT0	TxD	RxD	FFH
PCON#1	Power Control	87H	SMOD1	SMOD0	_	POF <sup>2</sup>	GF1	GF0	PD	IDL	00xxx000B
			D7	D6	D5	D4	D3	D2	D1	D0	
PSW*	Program Status Word	D0H	CY	AC	F0	RS1	RS0	OV	_	Р	000000x0B
RACAP2H# RACAP2L#	Timer 2 Capture High Timer 2 Capture Low	CBH CAH									00H 00H
SADDR# SADEN#	Slave Address Slave Address Mask	A9H B9H									00H 00H
SBUF	Serial Data Buffer	99H									xxxxxxxxB
ODOI	Genai Bala Banei	0011	9F	9E	9D	9C	9B	9A	99	98	XXXXXXXX
SCON*	Serial Control	98H	SM0/FE	SM1	SM2	REN	TB8	RB8	TI	RI	00H
SP	Stack Pointer	81H		0	0						07H
0.	Clack Former		8F	8E	8D	8C	8B	8A	89	88	] ""
TCON*	Timer Control	88H	TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0	00H
			CF	CE	CD	CC	СВ	CA	C9	C8	
T2CON*	Timer 2 Control	C8H	TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/T2	CP/RL2	00H
T2MOD#	Timer 2 Mode Control	C9H	-	-	-	_	_	-	T2OE	DCEN	xxxxxx00B
TH0	Timer High 0	8CH					•	•	•	•	00H
TH1	Timer High 1	8DH									00H
TH2#	Timer High 2	CDH									00H
TL0 TL1	Timer Low 0 Timer Low 1	8AH 8BH									00H 00H
TL2#	Timer Low 1	CCH									00H
TMOD	Timer Mode	89H	GATE	C/T	M1	MO	GATE	C/T	M1	MO	00H
CCDs ore	THITICI WICGE	0311	OAIL	O/ I	1911	IVIO	LOAIL		IVII	IVIO	0011

<sup>-</sup> set source.



SFRs are bit addressable. SFRs are modified from or added to the 80C51 SFRs.

Reserved bits.

### 89C51/89C52/89C54/89C58

#### FLASH EPROM MEMORY

#### **General Description**

The 89C51/89C52/89C54/89C58 FLASH reliably stores memory contents even after 100 erase and program cycles. The cell is designed to optimize the erase and programming mechanisms. In addition, the combination of advanced tunnel oxide processing and low internal electric fields for erase and programming operations produces reliable cycling.

#### **Features**

- FLASH EPROM internal program memory with Chip Erase
- Up to 64 k byte external program memory if the internal program memory is disabled (EA = 0)
- Programmable security bits
- 100 minimum erase/program cycles for each byte
- 10 year minimum data retention
- Programming support available from many popular vendors

#### OSCILLATOR CHARACTERISTICS

XTAL1 and XTAL2 are the input and output, respectively, of an inverting amplifier. The pins can be configured for use as an on-chip oscillator.

To drive the device from an external clock source, XTAL1 should be driven while XTAL2 is left unconnected. There are no requirements on the duty cycle of the external clock signal, because the input to the internal clock circuitry is through a divide-by-two flip-flop. However, minimum and maximum high and low times specified in the data sheet must be observed.

#### RESET

A reset is accomplished by holding the RST pin high for at least two machine cycles (24 oscillator periods), while the oscillator is running. To insure a good power-on reset, the RST pin must be high long enough to allow the oscillator time to start up (normally a few milliseconds) plus two machine cycles. At power-on, the voltage on  $V_{CC}$  and RST must come up at the same time for a proper start-up. Ports 1, 2, and 3 will asynchronously be driven to their reset condition when a voltage above  $V_{IH1}$  (min.) is applied to RESET.

The value on the  $\overline{\text{EA}}$  pin is latched when RST is deasserted and has no further effect.



### 89C51/89C52/89C54/89C58

#### LOW POWER MODES

#### **Stop Clock Mode**

The static design enables the clock speed to be reduced down to 0 MHz (stopped). When the oscillator is stopped, the RAM and Special Function Registers retain their values. This mode allows step-by-step utilization and permits reduced system power consumption by lowering the clock frequency down to any value. For lowest power consumption the Power Down mode is suggested.

#### **Idle Mode**

In the idle mode (see Table 2), the CPU puts itself to sleep while all of the on-chip peripherals stay active. The instruction to invoke the idle mode is the last instruction executed in the normal operating mode before the idle mode is activated. The CPU contents, the on-chip RAM, and all of the special function registers remain intact during this mode. The idle mode can be terminated either by any enabled interrupt (at which time the process is picked up at the interrupt service routine and continued), or by a hardware reset which starts the processor in the same manner as a power-on reset.

#### **Power-Down Mode**

To save even more power, a Power Down mode (see Table 2) can be invoked by software. In this mode, the oscillator is stopped and the instruction that invoked Power Down is the last instruction executed. The on-chip RAM and Special Function Registers retain their values down to 2.0 V and care must be taken to return  $V_{CC}$  to the minimum specified operating voltages before the Power Down Mode is terminated.

Either a hardware reset or external interrupt can be used to exit from Power Down. Reset redefines all the SFRs but does not change the on-chip RAM. An external interrupt allows both the SFRs and the on-chip RAM to retain their values.

To properly terminate Power Down the reset or external interrupt should not be executed before  $V_{CC}$  is restored to its normal operating level and must be held active long enough for the oscillator to restart and stabilize (normally less than 10ms).

With an external interrupt, INT0 and INT1 must be enabled and configured as level-sensitive. Holding the pin low restarts the oscillator but bringing the pin back high completes the exit. Once the interrupt is serviced, the next instruction to be executed after RETI will be the one following the instruction that put the device into Power Down.

#### **Design Consideration**

• When the idle mode is terminated by a hardware reset, the device normally resumes program execution, from where it left off, up to two machine cycles before the internal reset algorithm takes control. On-chip hardware inhibits access to internal RAM in this event, but access to the port pins is not inhibited. To eliminate the possibility of an unexpected write when Idle is terminated by reset, the instruction following the one that invokes Idle should not be one that writes to a port pin or to external memory.

#### ONCE™ Mode

The ONCE ("On-Circuit Emulation") Mode facilitates testing and debugging of systems without the device having to be removed from the circuit. The ONCE Mode is invoked by:

- 1. Pull ALE low while the device is in reset and PSEN is high;
- 2. Hold ALE low as RST is deactivated.

While the device is in ONCE Mode, the Port 0 pins go into a float state, and the other port pins and ALE and  $\overline{\text{PSEN}}$  are weakly pulled high. The oscillator circuit remains active. While the device is in this mode, an emulator or test CPU can be used to drive the circuit. Normal operation is restored when a normal reset is applied.

#### **Programmable Clock-Out**

A 50% duty cycle clock can be programmed to come out on P1.0. This pin, besides being a regular I/O pin, has two alternate functions. It can be programmed:

- 1. to input the external clock for Timer/Counter 2, or
- to output a 50% duty cycle clock ranging from 61Hz to 4MHz at a 16MHz operating frequency.

To configure the Timer/Counter 2 as a clock generator, bit C/T2 (in T2CON) must be cleared and bit T20E in T2MOD must be set. Bit TR2 (T2CON.2) also must be set to start the timer.

The Clock-Out frequency depends on the oscillator frequency and the reload value of Timer 2 capture registers (RCAP2H, RCAP2L) as shown in this equation:

$$\frac{\text{Oscillator Frequency}}{4 \times (65536 - \text{RCAP2H}, \text{RCAP2L})}$$

Where (RCAP2H,RCAP2L) = the content of RCAP2H and RCAP2L taken as a 16-bit unsigned integer.

In the Clock-Out mode Timer 2 roll-overs will not generate an interrupt. This is similar to when it is used as a baud-rate generator. It is possible to use Timer 2 as a baud-rate generator and a clock generator simultaneously. Note, however, that the baud-rate and the Clock-Out frequency will be the same.

Table 2. External Pin Status During Idle and Power-Down Mode

MODE	PROGRAM MEMORY	ALE	PSEN	PORT 0	PORT 1	PORT 2	PORT 3
Idle	Internal	1	1	Data	Data	Data	Data
Idle	External	1	1	Float	Data	Address	Data
Power-down	Internal	0	0	Data	Data	Data	Data
Power-down	External	0	0	Float	Data	Data	Data



Philips Semiconductors Product specification

## 80C51 8-bit microcontroller family 4K/8K/16K/32K Flash

### 89C51/89C52/89C54/89C58

#### **TIMER 2 OPERATION**

#### Timer 2

Timer 2 is a 16-bit Timer/Counter which can operate as either an event timer or an event counter, as selected by  $C/T2^*$  in the special function register T2CON (see Figure 1). Timer 2 has three operating modes: Capture, Auto-reload (up or down counting), and Baud Rate Generator, which are selected by bits in the T2CON as shown in Table 3.

#### Capture Mode

In the capture mode there are two options which are selected by bit EXEN2 in T2CON. If EXEN2=0, then timer 2 is a 16-bit timer or counter (as selected by C/T2\* in T2CON) which, upon overflowing sets bit TF2, the timer 2 overflow bit. This bit can be used to generate an interrupt (by enabling the Timer 2 interrupt bit in the IE register). If EXEN2= 1, Timer 2 operates as described above, but with the added feature that a 1- to -0 transition at external input T2EX causes the current value in the Timer 2 registers, TL2 and TH2, to be captured into registers RCAP2L and RCAP2H, respectively. In addition, the transition at T2EX causes bit EXF2 in T2CON to be set, and EXF2 like TF2 can generate an interrupt (which vectors to the same location as Timer 2 overflow interrupt. The Timer 2 interrupt service routine can interrogate TF2 and EXF2 to determine which event caused the interrupt). The capture mode is illustrated in Figure 2 (There is no reload value for TL2 and TH2 in this mode. Even when a capture event occurs from T2EX, the counter keeps on counting T2EX pin transitions or osc/12 pulses.).

#### Auto-Reload Mode (Up or Down Counter)

In the 16-bit auto-reload mode, Timer 2 can be configured (as either a timer or counter  $[C/T2^*$  in T2CON]) then programmed to count up or down. The counting direction is determined by bit DCEN (Down Counter Enable) which is located in the T2MOD register (see

Figure 3). When reset is applied the DCEN=0 which means Timer 2 will default to counting up. If DCEN bit is set, Timer 2 can count up or down depending on the value of the T2EX pin.

Figure 4 shows Timer 2 which will count up automatically since DCEN=0. In this mode there are two options selected by bit EXEN2 in T2CON register. If EXEN2=0, then Timer 2 counts up to 0FFFFH and sets the TF2 (Overflow Flag) bit upon overflow. This causes the Timer 2 registers to be reloaded with the 16-bit value in RCAP2L and RCAP2H. The values in RCAP2L and RCAP2H are preset by software means.

If EXEN2=1, then a 16-bit reload can be triggered either by an overflow or by a 1-to-0 transition at input T2EX. This transition also sets the EXF2 bit. The Timer 2 interrupt, if enabled, can be generated when either TF2 or EXF2 are 1.

In Figure 5 DCEN=1 which enables Timer 2 to count up or down. This mode allows pin T2EX to control the direction of count. When a logic 1 is applied at pin T2EX Timer 2 will count up. Timer 2 will overflow at 0FFFFH and set the TF2 flag, which can then generate an interrupt, if the interrupt is enabled. This timer overflow also causes the 16-bit value in RCAP2L and RCAP2H to be reloaded into the timer registers TL2 and TH2.

When a logic 0 is applied at pin T2EX this causes Timer 2 to count down. The timer will underflow when TL2 and TH2 become equal to the value stored in RCAP2L and RCAP2H. Timer 2 underflow sets the TF2 flag and causes 0FFFFH to be reloaded into the timer registers TL2 and TH2.

The external flag EXF2 toggles when Timer 2 underflows or overflows. This EXF2 bit can be used as a 17th bit of resolution if needed. The EXF2 flag does not generate an interrupt in this mode of operation.

	(MSE	3)						(LSB)	
	Т	F2 EXF2	RCLK	TCLK	EXEN2	TR2	C/T2	CP/RL2	
Symbol	Position	Name and Sig	nificance						
TF2	T2CON.7		Timer 2 overflow flag set by a Timer 2 overflow and must be cleared by software. TF2 will not be set when either RCLK or TCLK = 1.						
EXF2	T2CON.6	EXEN2 = 1. W interrupt routin	Timer 2 external flag set when either a capture or reload is caused by a negative transition on T2EX and EXEN2 = 1. When Timer 2 interrupt is enabled, EXF2 = 1 will cause the CPU to vector to the Timer 2 interrupt routine. EXF2 must be cleared by software. EXF2 does not cause an interrupt in up/down counter mode (DCEN = 1).						
RCLK	T2CON.5		Receive clock flag. When set, causes the serial port to use Timer 2 overflow pulses for its receive clock in modes 1 and 3. RCLK = 0 causes Timer 1 overflow to be used for the receive clock.						
TCLK	T2CON.4		Transmit clock flag. When set, causes the serial port to use Timer 2 overflow pulses for its transmit clock in modes 1 and 3. TCLK = 0 causes Timer 1 overflows to be used for the transmit clock.						
EXEN2	T2CON.3	transition on T	Timer 2 external enable flag. When set, allows a capture or reload to occur as a result of a negative transition on T2EX if Timer 2 is not being used to clock the serial port. EXEN2 = 0 causes Timer 2 to ignore events at T2EX.						
TR2	T2CON.2	Start/stop cont	rol for Time	2. A logic 1	starts the ti	mer.			
C/T2	T2CON.1	0 = I	Start/stop control for Timer 2. A logic 1 starts the timer.  Timer or counter select. (Timer 2) 0 = Internal timer (OSC/12) 1 = External event counter (falling edge triggered).						
CP/RL2	T2CON.0	Capture/Reloa cleared, auto-r	d flag. Whei eloads will c hen either R	n set, captur	es will occur with Timer 2	r on negativ	or negative t	transitions at	EXEN2 = 1. When T2EX when ced to auto-reload



Figure 1. Timer/Counter 2 (T2CON) Control Register

## 89C51/89C52/89C54/89C58

Table 3. Timer 2 Operating Modes

RCLK + TCLK	CP/RL2	TR2	MODE
0	0	1	16-bit Auto-reload
0	1	1	16-bit Capture
1	Х	1	Baud rate generator
X	Х	0	(off)

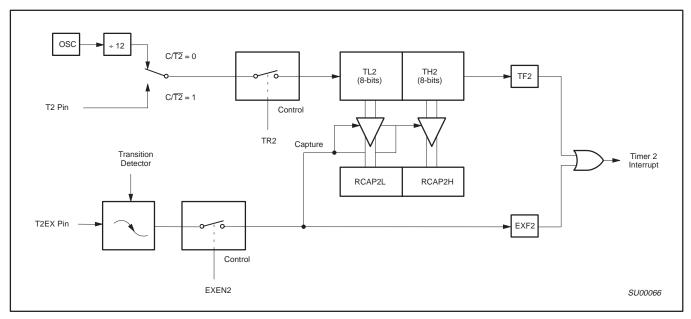


Figure 2. Timer 2 in Capture Mode

	Not Bit	Addressat	ole							
		_	_	_	_	_	_	T2OE	DCEN	
	Bit	7	6	5	4	3	2	1	0	
Symbol	Functi	on								
_	Not implemented, reserved for future use.*									
T2OE	Timer 2	2 Output E	nable bit.							
DCEN	Down	Count Ena	able bit. Whe	en set, this a	llows Timer	2 to be con	figured as a	n up/down o	counter.	
User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new features. In that case, the reset or inactive value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.										

Figure 3. Timer 2 Mode (T2MOD) Control Register



10

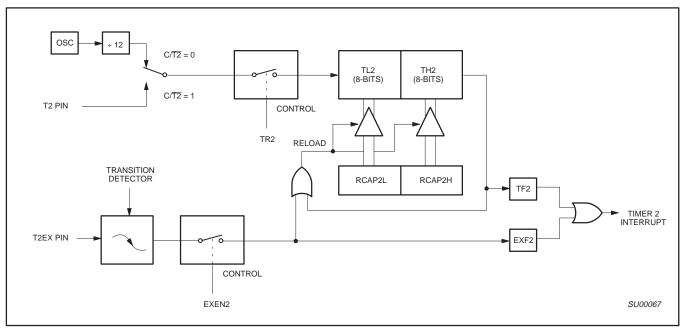


Figure 4. Timer 2 in Auto-Reload Mode (DCEN = 0)

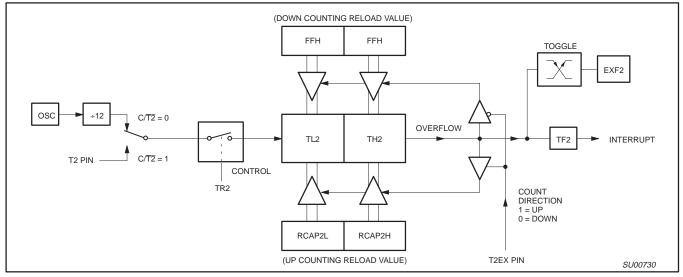


Figure 5. Timer 2 Auto Reload Mode (DCEN = 1)



### 89C51/89C52/89C54/89C58

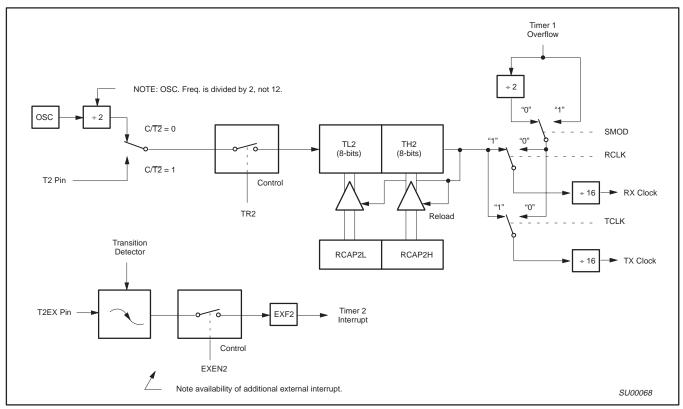


Figure 6. Timer 2 in Baud Rate Generator Mode

Table 4. Timer 2 Generated Commonly Used Baud Rates

Baud Rate	Oce From	Tim	er 2					
Baud Rate	Osc Freq	RCAP2H	RCAP2L					
375 k	12 MHz	FF	FF					
9.6 k	12 MHz	FF	D9					
2.8 k	12 MHz	FF	B2					
2.4 k	12 MHz	FF	64					
1.2 k	12 MHz	FE	C8					
300	12 MHz	FB	1E					
110	12 MHz	F2	AF					
300	6 MHz	FD	8F					
110	6 MHz	F9	57					

#### **Baud Rate Generator Mode**

Bits TCLK and/or RCLK in T2CON (Table 4) allow the serial port transmit and receive baud rates to be derived from either Timer 1 or Timer 2. When TCLK= 0, Timer 1 is used as the serial port transmit baud rate generator. When TCLK= 1, Timer 2 is used as the serial port transmit baud rate generator. RCLK has the same effect for the serial port receive baud rate. With these two bits, the serial port can have different receive and transmit baud rates – one generated by Timer 1, the other by Timer 2.

Figure 6 shows the Timer 2 in baud rate generation mode. The baud rate generation mode is like the auto-reload mode, in that a rollover in TH2 causes the Timer 2 registers to be reloaded with the 16-bit value in registers RCAP2H and RCAP2L, which are preset by software.

The baud rates in modes 1 and 3 are determined by Timer 2's overflow rate given below:

Modes 1 and 3 Baud Rates = 
$$\frac{\text{Timer 2 Overflow Rate}}{16}$$

The timer can be configured for either "timer" or "counter" operation. In many applications, it is configured for "timer" operation ( $C/\overline{T}2^*=0$ ). Timer operation is different for Timer 2 when it is being used as a baud rate generator.

Usually, as a timer it would increment every machine cycle (i.e., 1/12 the oscillator frequency). As a baud rate generator, it increments every state time (i.e., 1/2 the oscillator frequency). Thus the baud rate formula is as follows:

Modes 1 and 3 Baud Rates =

Where: (RCAP2H, RCAP2L) = The content of RCAP2H and RCAP2L taken as a 16-bit unsigned integer.

The Timer 2 as a baud rate generator mode shown in Figure 6, is valid only if RCLK and/or TCLK = 1 in T2CON register. Note that a rollover in TH2 does not set TF2, and will not generate an interrupt. Thus, the Timer 2 interrupt does not have to be disabled when Timer 2 is in the baud rate generator mode. Also if the EXEN2 (T2 external enable flag) is set, a 1-to-0 transition in T2EX (Timer/counter 2 trigger input) will set EXF2 (T2 external flag) but will not cause a reload from (RCAP2H, RCAP2L) to (TH2,TL2). Therefore when Timer 2 is in use as a baud rate generator, T2EX can be used as an additional external interrupt, if needed.



### 89C51/89C52/89C54/89C58

When Timer 2 is in the baud rate generator mode, one should not try to read or write TH2 and TL2. As a baud rate generator, Timer 2 is incremented every state time (osc/2) or asynchronously from pin T2; under these conditions, a read or write of TH2 or TL2 may not be accurate. The RCAP2 registers may be read, but should not be written to, because a write might overlap a reload and cause write and/or reload errors. The timer should be turned off (clear TR2) before accessing the Timer 2 or RCAP2 registers.

Table 4 shows commonly used baud rates and how they can be obtained from Timer 2.

#### **Summary Of Baud Rate Equations**

Timer 2 is in baud rate generating mode. If Timer 2 is being clocked through pin T2(P1.0) the baud rate is:

Baud Rate = 
$$\frac{\text{Timer 2 Overflow Rate}}{16}$$

If Timer 2 is being clocked internally, the baud rate is:

Baud Rate = 
$$\frac{f_{OSC}}{[32 \times [65536 - (RCAP2H, RCAP2L)]]}$$

Where f<sub>OSC</sub>= Oscillator Frequency

To obtain the reload value for RCAP2H and RCAP2L, the above equation can be rewritten as:

RCAP2H, RCAP2L = 
$$65536 - \left(\frac{f_{OSC}}{32 \times Baud \ Rate}\right)$$

#### **Timer/Counter 2 Set-up**

Except for the baud rate generator mode, the values given for T2CON do not include the setting of the TR2 bit. Therefore, bit TR2 must be set, separately, to turn the timer on. see Table 5 for set-up of Timer 2 as a timer. Also see Table 6 for set-up of Timer 2 as a counter.

Table 5. Timer 2 as a Timer

	T2C	CON
MODE	INTERNAL CONTROL (Note 1)	EXTERNAL CONTROL (Note 2)
16-bit Auto-Reload	00H	08H
16-bit Capture	01H	09H
Baud rate generator receive and transmit same baud rate	34H	36H
Receive only	24H	26H
Transmit only	14H	16H

Table 6. Timer 2 as a Counter

	TMOD				
MODE	INTERNAL CONTROL (Note 1)	EXTERNAL CONTROL (Note 2)			
16-bit	02H	0AH			
Auto-Reload	03H	0BH			

#### NOTES:

- 1. Capture/reload occurs only on timer/counter overflow.
- 2. Capture/reload occurs on timer/counter overflow and a 1-to-0 transition on T2EX (P1.1) pin except when Timer 2 is used in the baud rate generator mode.



### 89C51/89C52/89C54/89C58

#### **Enhanced UART**

The UART operates in all of the usual modes that are described in the first section of *Data Handbook IC20, 80C51-Based 8-Bit Microcontrollers*. In addition the UART can perform framing error detect by looking for missing stop bits, and automatic address recognition. The UART also fully supports multiprocessor communication as does the standard 80C51 UART.

When used for framing error detect the UART looks for missing stop bits in the communication. A missing bit will set the FE bit in the SCON register. The FE bit shares the SCON.7 bit with SM0 and the function of SCON.7 is determined by PCON.6 (SMOD0) (see Figure 7). If SMOD0 is set then SCON.7 functions as FE. SCON.7 functions as SM0 when SMOD0 is cleared. When used as FE SCON.7 can only be cleared by software. Refer to Figure 8.

#### **Automatic Address Recognition**

Automatic Address Recognition is a feature which allows the UART to recognize certain addresses in the serial bit stream by using hardware to make the comparisons. This feature saves a great deal of software overhead by eliminating the need for the software to examine every serial address which passes by the serial port. This feature is enabled by setting the SM2 bit in SCON. In the 9 bit UART modes, mode 2 and mode 3, the Receive Interrupt flag (RI) will be automatically set when the received byte contains either the "Given" address or the "Broadcast" address. The 9 bit mode requires that the 9th information bit is a 1 to indicate that the received information is an address and not data. Automatic address recognition is shown in Figure 9.

The 8 bit mode is called Mode 1. In this mode the RI flag will be set if SM2 is enabled and the information received has a valid stop bit following the 8 address bits and the information is either a Given or Broadcast address.

Mode 0 is the Shift Register mode and SM2 is ignored.

Using the Automatic Address Recognition feature allows a master to selectively communicate with one or more slaves by invoking the Given slave address or addresses. All of the slaves may be contacted by using the Broadcast address. Two special Function Registers are used to define the slave's address, SADDR, and the address mask, SADEN. SADEN is used to define which bits in the SADDR are to b used and which bits are "don't care". The SADEN mask can be logically ANDed with the SADDR to create the "Given" address which the master will use for addressing each of the slaves. Use of the Given address allows multiple slaves to be recognized while excluding others. The following examples will help to show the versatility of this scheme:

Slave 0 SADDR = 1100 0000

SADEN = 1111 1101Given = 1100 00X0

Slave 1	SADDR	=	1100 0000
	SADEN	=	<u>1111 1110</u>
	Given	=	1100 000X

In the above example SADDR is the same and the SADEN data is used to differentiate between the two slaves. Slave 0 requires a 0 in bit 0 and it ignores bit 1. Slave 1 requires a 0 in bit 1 and bit 0 is ignored. A unique address for Slave 0 would be 1100 0010 since slave 1 requires a 0 in bit 1. A unique address for slave 1 would be 1100 0001 since a 1 in bit 0 will exclude slave 0. Both slaves can be selected at the same time by an address which has bit 0 = 0 (for slave 0) and bit 1 = 0 (for slave 1). Thus, both could be addressed with 1100 0000.

In a more complex system the following could be used to select slaves 1 and 2 while excluding slave 0:

Slave 0	SADDR	=	1100	0000
	SADEN	=	<u>1111</u>	1001
	Given	=	1100	0XX0
Slave 1	SADDR	=	1110	0000
	SADEN	=	1111	1010
	Given	=	1110	0X0X
Slave 2	SADDR	=	1110	0000
	SADEN	=	<u>1111</u>	1100
	Given	=	1110	00XX

In the above example the differentiation among the 3 slaves is in the lower 3 address bits. Slave 0 requires that bit 0=0 and it can be uniquely addressed by 1110 0110. Slave 1 requires that bit 1=0 and it can be uniquely addressed by 1110 and 0101. Slave 2 requires that bit 2=0 and its unique address is 1110 0011. To select Slaves 0 and 1 and exclude Slave 2 use address 1110 0100, since it is necessary to make bit 2=1 to exclude slave 2.

The Broadcast Address for each slave is created by taking the logical OR of SADDR and SADEN. Zeros in this result are trended as don't-cares. In most cases, interpreting the don't-cares as ones, the broadcast address will be FF hexadecimal.

Upon reset SADDR (SFR address 0A9H) and SADEN (SFR address 0B9H) are leaded with 0s. This produces a given address of all "don't cares" as well as a Broadcast address of all "don't cares". This effectively disables the Automatic Addressing mode and allows the microcontroller to use standard 80C51 type UART drivers which do not make use of this feature.



	S	CON Addr	ess = 98H							Reset Value = 0000 0000B
	Bit Add	dressable								
		SM0/FE	SM1	SM2	REN	TB8	RB8	TI	RI	
	Bit:	7	6	5	4	3	2	1	0	
	(	(SMOD0 = 0)	/1)*							
Symbol	Func	tion								
FE		ing Error bit								it is not cleared by valid e FE bit.
SM0	Seria	l Port Mode	Bit 0, (SM	OD0 must :	= 0 to acce	ss bit SM0)				
SM1	Seria	I Port Mode	Bit 1							
	SM0	SM1	Mode	Descr	iption	Baud Rate	**			
	0	0	0	shift re	0	f <sub>OSC</sub> /12				
	0	1	1	8-bit U		variable	4 /00			
	1 1	0 1	2 3	9-bit U 9-bit U		f <sub>OSC</sub> /64 or variable	IOSC/32			
SM2	recei <sup>.</sup> In Mo	ved 9th data	bit (RB8) 2 = 1 then f	is 1, indicat	ting an add	lress, and th d unless a va	e received	byte is a G	iven or Br	ot be set unless the padcast Address. le received byte is a
REN	Enab	les serial re	ception. Se	t by softwa	are to enab	le reception	Clear by s	oftware to	disable red	ception.
ГВ8	The 9	9th data bit t	hat will be	transmitted	I in Modes	2 and 3. Set	or clear by	software a	s desired	
RB8		odes 2 and 3 ode 0, RB8 is			was receiv	ed. In Mode	1, if SM2 =	= 0, RB8 is	the stop b	it that was received.
TI		Transmit interrupt flag. Set by hardware at the end of the 8th bit time in Mode 0, or at the beginning of the stop bit in the other modes, in any serial transmission. Must be cleared by software.								
RI		eive interrupt ther modes,								ough the stop bit time in
r <b>E:</b> OD0 is locate sc = oscillato										SU00043

Figure 7. SCON: Serial Port Control Register



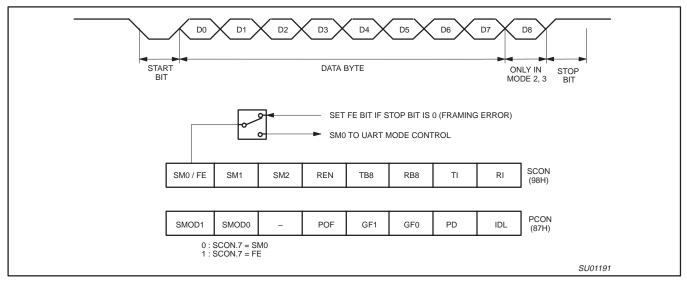


Figure 8. UART Framing Error Detection

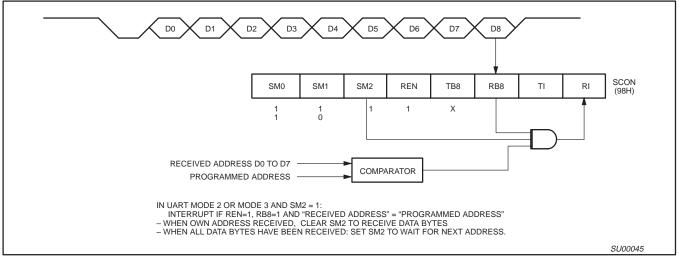


Figure 9. UART Multiprocessor Communication, Automatic Address Recognition



### 89C51/89C52/89C54/89C58

#### **Interrupt Priority Structure**

The 89C51/89C52/89C54/89C58 have a 6-source four-level interrupt structure.

There are 3 SFRs associated with the four-level interrupt. They are the IE, IP, and IPH. (See Figures 10, 11, and 12.) The IPH (Interrupt Priority High) register makes the four-level interrupt structure possible. The IPH is located at SFR address B7H. The structure of the IPH register and a description of its bits is shown in Figure 12.

The function of the IPH SFR is simple and when combined with the IP SFR determines the priority of each interrupt. The priority of each interrupt is determined as shown in the following table:

PRIORI	TY BITS	INTERRUPT PRIORITY I EVEL			
IPH.x	IP.x	INTERRUPT PRIORITY LEVEL			
0	0	Level 0 (lowest priority)			
0	1	Level 1			
1	0	Level 2			
1	1	Level 3 (highest priority)			

There are four interrupt levels rather than two as on the 80C51. An interrupt will be serviced as long as an interrupt of equal or higher priority is not already being serviced. If an interrupt of equal or higher level priority is being serviced, the new interrupt will wait until it is finished before being serviced. If a lower priority level interrupt is being serviced, it will be stopped and the new interrupt serviced. When the new interrupt is finished, the lower priority level interrupt that was stopped will be completed.

Table 7. Interrupt Table

SOURCE	POLLING PRIORITY	REQUEST BITS	HARDWARE CLEAR?	VECTOR ADDRESS
X0	1	IE0	N (L) <sup>1</sup> Y (T) <sup>2</sup>	03H
T0	2	TP0	Υ	0BH
X1	3	IE1	N (L) Y (T)	13H
T1	4	TF1	Υ	1BH
SP	5	RI, TI	N	23H
T2	6	TF2, EXF2	N	2BH

#### NOTES:

- L = Level activated
- 2. T = Transition activated

		7	6	5	4	3	2	1	0
	IE (0A8H)	EA	_	ET2	ES	ET1	EX1	ET0	EX0
			Bit = 1 ena Bit = 0 dis		nterrupt.				
BIT	SYMBOL	FUNC	TION						
IE.7	EA						disabled. enable bit.		each inte
IE.6	_			•	ed for futu	_			
IE.5	ET2	Timer	2 interrup	t enable b	it.				
IE.4	ES	Serial	Port inter	upt enabl	e bit.				
IE.3	ET1	Timer	1 interrup	t enable b	it.				
IE.2	EX1	Extern	External interrupt 1 enable bit.						
IE.1	ET0	Timer	0 interrup	t enable b	it.				
IE.0	EX0	Extern	al interrup	ot 0 enable	e bit.				

Figure 10. IE Registers



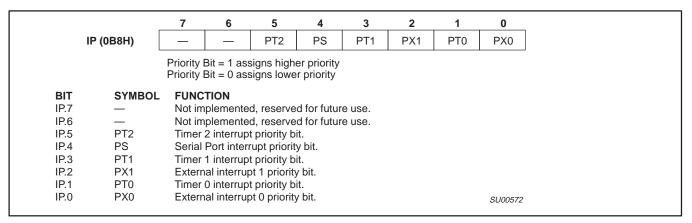


Figure 11. IP Registers

		7	6	5	4	3	2	1	0
IPH	IPH (B7H)		_	PT2H	PSH	PT1H	PX1H	PT0H	PX0H
				signs high signs lowe					
BIT	SYMBOL	FUNC	FUNCTION						
IPH.7	_	Not im	Not implemented, reserved for future use.						
IPH.6	_	Not im	Not implemented, reserved for future use.						
IPH.5	PT2H	Timer	Timer 2 interrupt priority bit high.						
IPH.4	PSH	Serial	Serial Port interrupt priority bit high.						
IPH.3	PT1H	Timer	Timer 1 interrupt priority bit high.						
IPH.2	PX1H	Extern	External interrupt 1 priority bit high.						
IPH.1	PT0H	Timer	Timer 0 interrupt priority bit high.						
IPH.0	PX0H	Extern	al interrup	t 0 priority	y bit high.				SU010

Figure 12. IPH Registers



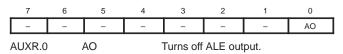
### 89C51/89C52/89C54/89C58

#### **Reduced EMI Mode**

The AO bit (AUXR.0) in the AUXR register when set disables the ALE output.

#### **Reduced EMI Mode**

#### AUXR (8EH)



#### **Dual DPTR**

The dual DPTR structure (see Figure 13) is a way by which the chip will specify the address of an external data memory location. There are two 16-bit DPTR registers that address the external memory, and a single bit called DPS = AUXR1/bit0 that allows the program code to switch between them.

New Register Name: AUXR1#

SFR Address: A2HReset Value: xxxx00x0B

#### AUXR1 (A2H)

7	6	5	4	3	2	1	0
-	-	-	-	GF2	0	-	DPS

Where:

DPS = AUXR1/bit0 = Switches between DPTR0 and DPTR1.

Select Reg	DPS
DPTR0	0
DPTR1	1

The DPS bit status should be saved by software when switching between DPTR0 and DPTR1.

The GF0 bit is a general purpose user-defined flag. Note that bit 2 is not writable and is always read as a zero. This allows the DPS bit to be quickly toggled simply by executing an INC AUXR1 instruction without affecting the GF2 bit.

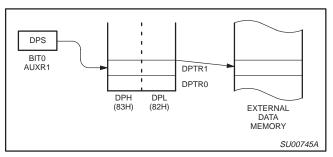


Figure 13.

#### **DPTR Instructions**

The instructions that refer to DPTR refer to the data pointer that is currently selected using the AUXR1/bit 0 register. The six instructions that use the DPTR are as follows:

INC DPTR	Increments the data pointer by 1
MOV DPTR, #data16	Loads the DPTR with a 16-bit constant
MOV A, @ A+DPTR	Move code byte relative to DPTR to ACC
MOVX A, @ DPTR	Move external RAM (16-bit address) to ACC
MOVX @ DPTR , A	Move ACC to external RAM (16-bit address)
JMP @ A + DPTR	Jump indirect relative to DPTR

The data pointer can be accessed on a byte-by-byte basis by specifying the low or high byte in an instruction which accesses the SFRs. See application note AN458 for more details.



### 89C51/89C52/89C54/89C58

### **ABSOLUTE MAXIMUM RATINGS**1, 2, 3

PARAMETER	RATING	UNIT
Operating temperature under bias	0 to +70 or -40 to +85	°C
Storage temperature range	-65 to +150	°C
Voltage on EA/V <sub>PP</sub> pin to V <sub>SS</sub>	0 to +13.0	V
Voltage on any other pin to V <sub>SS</sub>	-0.5 to +6.5	V
Maximum I <sub>OL</sub> per I/O pin	15	mA
Power dissipation (based on package heat transfer limitations, not device power consumption)	1.5	W

#### NOTES:

- 1. Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any conditions other than those described in the AC and DC Electrical Characteristics section of this specification is not implied.
- This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maximum. Parameters are valid over operating temperature range unless otherwise specified. All voltages are with respect to V<sub>SS</sub> unless otherwise noted.

#### **AC ELECTRICAL CHARACTERISTICS**

 $T_{amb} = 0$ °C to +70°C or -40°C to +85°C

SYMBOL	PARAMETER	CLOCK FR RANG	UNIT	
		MIN	MAX	
1/t <sub>CLCL</sub>	Oscillator frequency: U (33MHz)	0	33	MHz



### 89C51/89C52/89C54/89C58

#### DC ELECTRICAL CHARACTERISTICS

 $T_{amb} = 0^{\circ}C$  to +70°C or -40°C to +85°C; 5 V ±10%;  $V_{SS} = 0$  V

OVMDOL	DADAMETER	TEST		UNIT			
SYMBOL	PARAMETER	CONDITIONS	MIN	TYP <sup>1</sup>	MAX	UNIT	
V <sub>IL</sub>	Input low voltage	4.5 V < V <sub>CC</sub> < 5.5 V	-0.5		0.2 V <sub>CC</sub> -0.1	V	
V <sub>IH</sub>	Input high voltage (ports 0, 1, 2, 3, EA)		0.2 V <sub>CC</sub> +0.9		V <sub>CC</sub> +0.5	V	
V <sub>IH1</sub>	Input high voltage, XTAL1, RST		0.7 V <sub>CC</sub>		V <sub>CC</sub> +0.5	V	
V <sub>OL</sub>	Output low voltage, ports 1, 2, 3 8	$V_{CC} = 4.5 \text{ V}$ $I_{OL} = 1.6 \text{ mA}^2$			0.4	V	
V <sub>OL1</sub>	Output low voltage, port 0, ALE, PSEN 7, 8	$V_{CC} = 4.5 \text{ V}$ $I_{OL} = 3.2 \text{ mA}^2$			0.4	V	
V <sub>OH</sub>	Output high voltage, ports 1, 2, 3 <sup>3</sup>	V <sub>CC</sub> = 4.5 V I <sub>OH</sub> = -30 μA	V <sub>CC</sub> - 0.7			V	
V <sub>OH1</sub>	Output high voltage (port 0 in external bus mode), ALE <sup>9</sup> , PSEN <sup>3</sup>	$V_{CC} = 4.5 \text{ V}$ $I_{OH} = -3.2 \text{ mA}$	V <sub>CC</sub> - 0.7			V	
I <sub>IL</sub>	Logical 0 input current, ports 1, 2, 3	V <sub>IN</sub> = 0.4 V	-1		-75	μΑ	
I <sub>TL</sub>	Logical 1-to-0 transition current, ports 1, 2, 3 <sup>6</sup>	V <sub>IN</sub> = 2.0 V See Note 4			-650	μΑ	
ILI	Input leakage current, port 0	$0.45 < V_{IN} < V_{CC} - 0.3$			±10	μΑ	
I <sub>CC</sub>	Power supply current (see Figure 21): Active mode (see Note 5) Idle mode (see Note 5)	See Note 5					
	Power-down mode or clock stopped (see Figure 25 for conditions)	$T_{amb} = 0$ °C to $70$ °C $T_{amb} = -40$ °C to $+85$ °C		3	100 125	μA μA	
R <sub>RST</sub>	Internal reset pull-down resistor		40		225	kΩ	
C <sub>IO</sub>	Pin capacitance <sup>10</sup> (except EA)				15	pF	

#### NOTES:

- 1. Typical ratings are not guaranteed. The values listed are at room temperature, 5 V.
- Capacitive loading on ports 0 and 2 may cause spurious noise to be superimposed on the VOLs of ALE and ports 1 and 3. The noise is due to external bus capacitance discharging into the port 0 and port 2 pins when these pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100pF), the noise pulse on the ALE pin may exceed 0.8V. In such cases, it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt Trigger STROBE input. I<sub>OL</sub> can exceed these conditions provided that no single output sinks more than 5 mA and no more than two outputs exceed the test conditions.
- 3. Capacitive loading on ports 0 and 2 may cause the  $V_{OH}$  on ALE and PSEN to momentarily fall below the  $V_{CC}$ -0.7 specification when the address bits are stabilizing.
- Pins of ports 1, 2 and 3 source a transition current when they are being externally driven from 1 to 0. The transition current reaches its maximum value when V<sub>IN</sub> is approximately 2 V.
- 5. See Figures 22 through 25 for I<sub>CC</sub> test conditions and Figure 21 for I<sub>CC</sub> vs Freq.

Active mode: I<sub>CC(MAX)</sub> = (0.9 × FREQ. + 20)mA Idle mode: I<sub>CC(MAX)</sub> = (0.37 × FREQ. +1.0)mA
6. This value applies to T<sub>amb</sub> = 0°C to +70°C.

- Load capacitance for port 0, ALE, and PSEN = 100pF, load capacitance for all other outputs = 80 pF.
- Under steady state (non-transient) conditions, I<sub>OL</sub> must be externally limited as follows:

Maximum IOL per port pin: 15 mA (\*NOTE: This is 85°C specification.)

Maximum I<sub>OL</sub> per 8-bit port: 26 mA Maximum total I<sub>OL</sub> for all outputs: 71 mA

If I<sub>OL</sub> exceeds the test condition, V<sub>OL</sub> may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.

- ALE is tested to  $V_{OH1}$ , except when ALE is off then  $V_{OH}$  is the voltage specification.
- 10. Pin capacitance is characterized but not tested. Pin capacitance is less than 25 pF. Pin capacitance of ceramic package is less than 15 pF (except EA is 25 pF).



### 89C51/89C52/89C54/89C58

#### **AC ELECTRICAL CHARACTERISTICS**

 $T_{amb} = 0$ °C to +70°C or -40°C to +85°C,  $V_{CC} = 5 \text{ V} \pm 10\%$ ,  $V_{SS} = 0\text{V}^{1, 2, 3}$ 

			VARIABL	E CLOCK <sup>4</sup>	33MHz			
SYMBOL	FIGURE	PARAMETER	MIN	MAX	MIN	MAX	TINU	
1/t <sub>CLCL</sub> 14		Oscillator frequency Speed versions: I;J;U (33 MHz)	3.5	33	3.5	33	MH	
t <sub>LHLL</sub>	14	ALE pulse width	2t <sub>CLCL</sub> -40		21		ns	
t <sub>AVLL</sub>	14	Address valid to ALE low	t <sub>CLCL</sub> -25		5		ns	
t <sub>LLAX</sub>	14	Address hold after ALE low	t <sub>CLCL</sub> -25		5		ns	
t <sub>LLIV</sub>	14	ALE low to valid instruction in		4t <sub>CLCL</sub> -65		55	ns	
t <sub>LLPL</sub>	14	ALE low to PSEN low	t <sub>CLCL</sub> -25		5		ns	
t <sub>PLPH</sub>	14	PSEN pulse width	3t <sub>CLCL</sub> -45		45		ns	
t <sub>PLIV</sub>	14	PSEN low to valid instruction in		3t <sub>CLCL</sub> -60		30	ns	
t <sub>PXIX</sub>	14	Input instruction hold after PSEN	0		0		ns	
t <sub>PXIZ</sub>	14	Input instruction float after PSEN		t <sub>CLCL</sub> -25		5	ns	
t <sub>AVIV</sub>	14	Address to valid instruction in		5t <sub>CLCL</sub> -80		70	ns	
t <sub>PLAZ</sub>	14	PSEN low to address float		10		10	ns	
Data Memo	ory							
t <sub>RLRH</sub>	15, 16	RD pulse width	6t <sub>CLCL</sub> -100		82		ns	
t <sub>WLWH</sub>	15, 16	WR pulse width	6t <sub>CLCL</sub> -100		82		ns	
t <sub>RLDV</sub>	15, 16	RD low to valid data in		5t <sub>CLCL</sub> -90		60	ns	
t <sub>RHDX</sub>	15, 16	Data hold after RD	0		0		ns	
t <sub>RHDZ</sub>	15, 16	Data float after RD		2t <sub>CLCL</sub> -28		32	ns	
t <sub>LLDV</sub>	15, 16	ALE low to valid data in		8t <sub>CLCL</sub> -150		90	ns	
t <sub>AVDV</sub>	15, 16	Address to valid data in		9t <sub>CLCL</sub> -165		105	ns	
t <sub>LLWL</sub>	15, 16	ALE low to RD or WR low	3t <sub>CLCL</sub> -50	3t <sub>CLCL</sub> +50	40	140	ns	
t <sub>AVWL</sub>	15, 16	Address valid to WR low or RD low	4t <sub>CLCL</sub> -75	0202	45		ns	
t <sub>QVWX</sub>	15, 16	Data valid to WR transition	t <sub>CLCL</sub> -30		0		ns	
t <sub>WHQX</sub>	15, 16	Data hold after WR	t <sub>CLCL</sub> -25		5		ns	
t <sub>QVWH</sub>	16	Data valid to WR high	7t <sub>CLCL</sub> -130		80		ns	
t <sub>RLAZ</sub>	15, 16	RD low to address float	OLOL	0		0	ns	
twhlh	15, 16	RD or WR high to ALE high	t <sub>CLCL</sub> -25	t <sub>CLCL</sub> +25	5	55	ns	
External C	lock	5 5	OLOL	OLOL				
t <sub>CHCX</sub>	18	High time	17	t <sub>CLCL</sub> -t <sub>CLCX</sub>			ns	
t <sub>CLCX</sub>	18	Low time	17	t <sub>CLCL</sub> -t <sub>CHCX</sub>			ns	
t <sub>CLCH</sub>	18	Rise time	1	5			ns	
t <sub>CHCL</sub>	18	Fall time	1	5			ns	
Shift Regis		-	1	<u> </u>			1	
t <sub>XLXL</sub>	17	Serial port clock cycle time	12t <sub>CLCL</sub>	<del>                                     </del>	360		ns	
t <sub>QVXH</sub>	17	Output data setup to clock rising edge	10t <sub>CLCL</sub> -133		167	<del>                                     </del>	ns	
t <sub>XHQX</sub>	17	Output data hold after clock rising edge	2t <sub>CLCL</sub> -80	<del>                                     </del>	50	<del>                                     </del>	ns	
t <sub>XHQX</sub>	17	Input data hold after clock rising edge	0	<del>                                     </del>	0	<del>                                     </del>	ns	
t <sub>XHDV</sub>	17	Clock rising edge to input data valid	<del>                                     </del>	10t <sub>CLCL</sub> -133		167	ns	

#### NOTES:

- Parameters are valid over operating temperature range unless otherwise specified.
   Load capacitance for port 0, ALE, and PSEN = 100 pF, load capacitance for all other outputs = 80 pF.
   Interfacing the microcontroller to devices with float times up to 45 ns is permitted. This limited bus contention will not cause damage to Port 0 drivers.
- 4. Parts are guaranteed to operate down to 0 Hz.



### 89C51/89C52/89C54/89C58

#### **EXPLANATION OF THE AC SYMBOLS**

Each timing symbol has five characters. The first character is always 't' (= time). The other characters, depending on their positions, indicate the name of a signal or the logical status of that signal. The designations are:

A - Address

C - Clock

D - Input data

H - Logic level high

I – Instruction (program memory contents)

L - Logic level low, or ALE

P - PSEN

Q - Output data

 $R - \overline{RD}$  signal

t - Time

V - Valid

W- WR signal

X - No longer a valid logic level

Z - Float

**Examples:** t<sub>AVLL</sub> = Time for address valid to ALE low.

 $t_{LLPL}$  =Time for ALE low to  $\overline{PSEN}$  low.

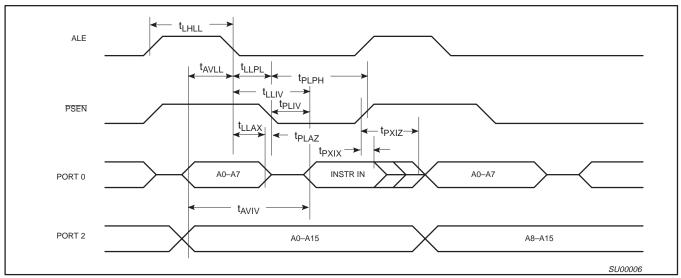


Figure 14. External Program Memory Read Cycle

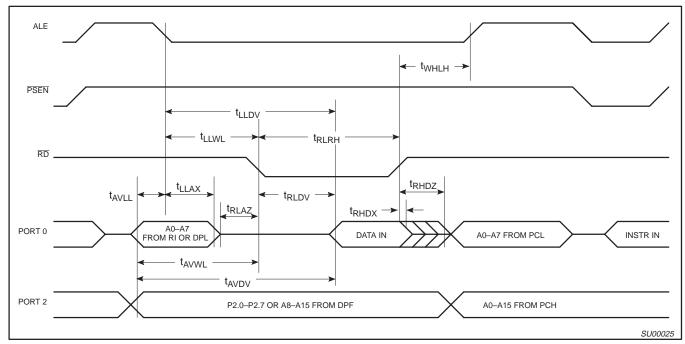


Figure 15. External Data Memory Read Cycle



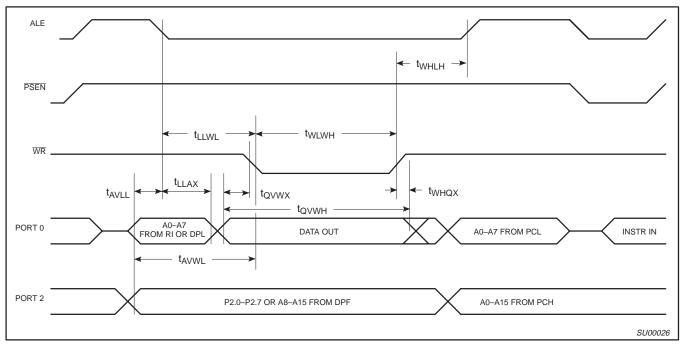


Figure 16. External Data Memory Write Cycle

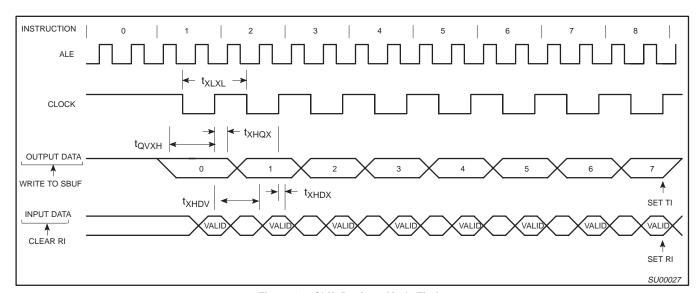


Figure 17. Shift Register Mode Timing

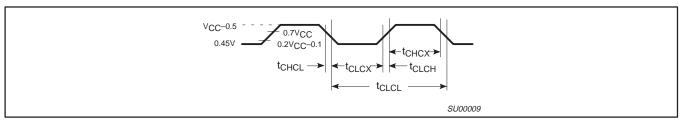


Figure 18. External Clock Drive



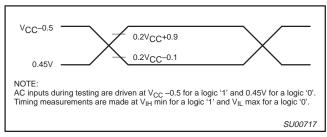


Figure 19. AC Testing Input/Output

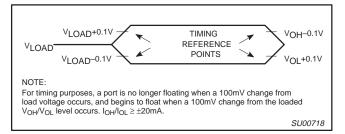
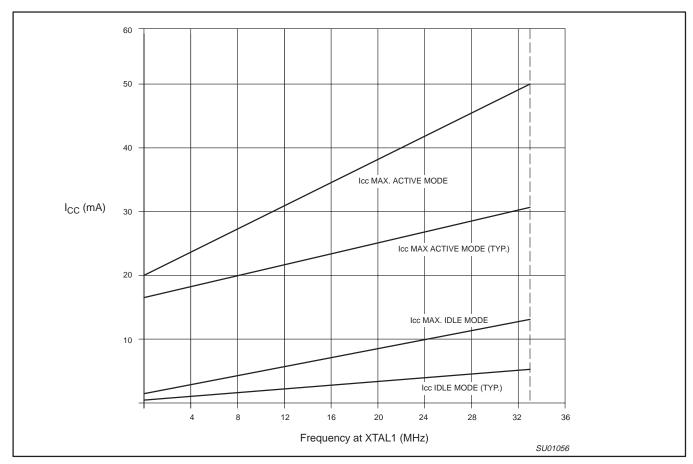


Figure 20. Float Waveform



 $\mbox{Figure 21. I}_{\mbox{CC}} \mbox{ vs. FREQ} \\ \mbox{Valid only within frequency specifications of the device under test} \\$ 



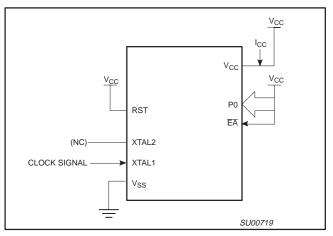


Figure 22. I<sub>CC</sub> Test Condition, Active Mode All other pins are disconnected

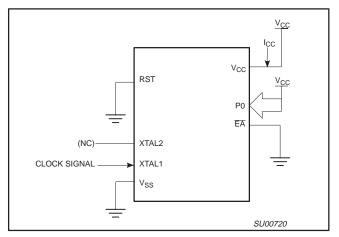


Figure 23. I<sub>CC</sub> Test Condition, Idle Mode All other pins are disconnected

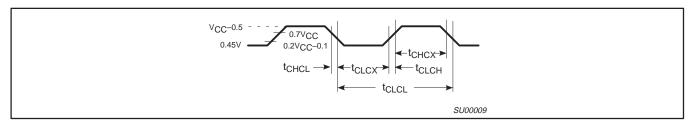


Figure 24. Clock Signal Waveform for  $I_{CC}$  Tests in Active and Idle Modes  $t_{CLCH} = t_{CHCL} = 5 ns$ 

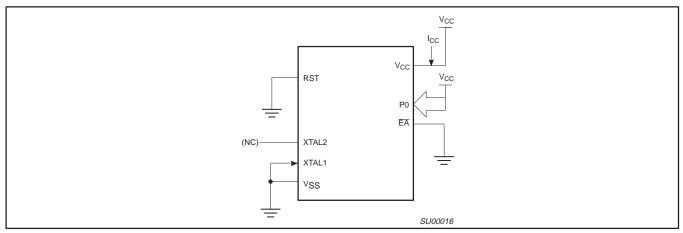


Figure 25.  $I_{CC}$  Test Condition, Power Down Mode All other pins are disconnected.  $V_{CC}$  = 2V to 5.5V



## 89C51/89C52/89C54/89C58

#### **Security**

The security feature protects against software piracy and prevents the contents of the FLASH from being read. The Security Lock bits are located in FLASH. The 89C51/89C52/89C54/89C58 has 3 programmable security lock bits that will provide different levels of protection for the on-chip code and data (see Table 8). Unlike the ROM and OTP versions, the security lock bits are independent. LB3 includes the security protection of LB1.

#### Table 8.

SECURITY LOCK BITS <sup>1</sup>	PROTECTION DESCRIPTION				
Level	PROTECTION DESCRIPTION				
LB1	MOVC instructions executed from external program memory are disabled from fetching code bytes from internal memory.				
LB2	Program verification is disabled				
LB3	External execution is disabled.				

#### NOTE:

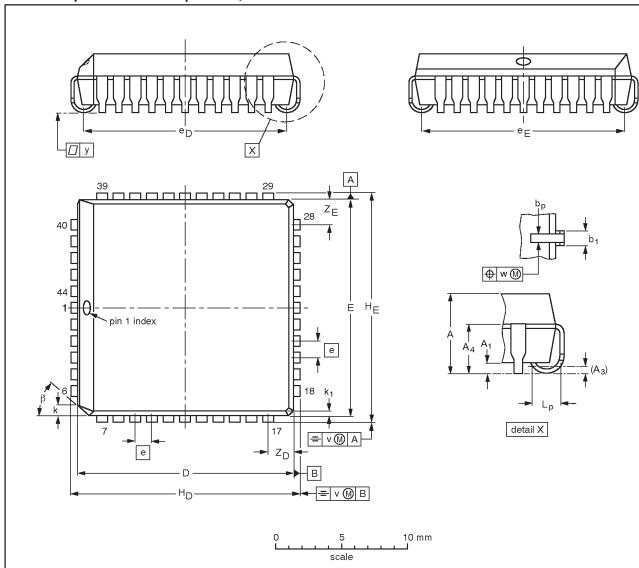


<sup>1.</sup> The security lock bits are independent.

## 89C51/89C52/89C54/89C58

PLCC44: plastic leaded chip carrier; 44 leads

SOT187-2



#### DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

UNIT	A	A <sub>1</sub> min.	A <sub>3</sub>	A <sub>4</sub> max.	bp	b <sub>1</sub>	D <sup>(1)</sup>	E <sup>(1)</sup>	е	e <sub>D</sub>	еE	H <sub>D</sub>	HE	k	k <sub>1</sub> max.	Lp	٧	w	у	Z <sub>D</sub> <sup>(1)</sup> max.	Z <sub>E</sub> <sup>(1)</sup> max.	β
mm	4.57 4.19	0.51	0.25	3.05	0.53 0.33	0.81 0.66	16.66 16.51	16.66 16.51	1.27	ı	16.00 14.99		1		0.51	1.44 1.02	0.18	0.18	0.10	2.16	2.16	45°
inches	0.180 0.165	0.020	0.01	0.12			0.656 0.650		0.05	ı	0.630 0.590		1			0.057 0.040	0.007	0.007	0.004	0.085	0.085	45

#### Note

1. Plastic or metal protrusions of 0.01 inches maximum per side are not included.

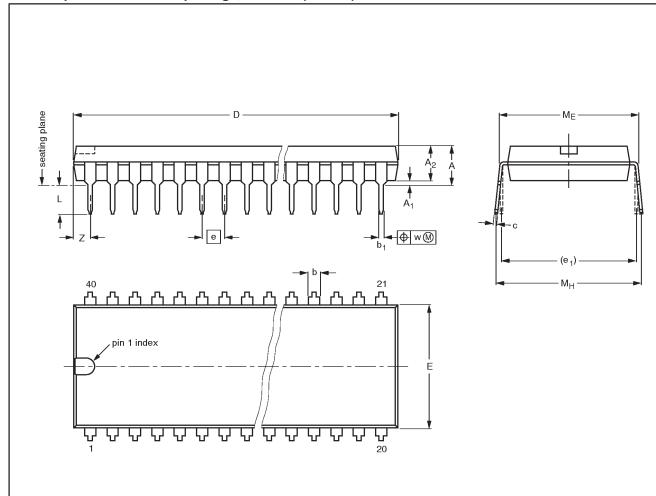
OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT187-2	112E10	MO-047AC			<del>-95-02-25-</del> 97-12-16

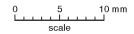


### DIP40: plastic dual in-line package; 40 leads (600 mil)

SOT129-1

Product specification





#### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

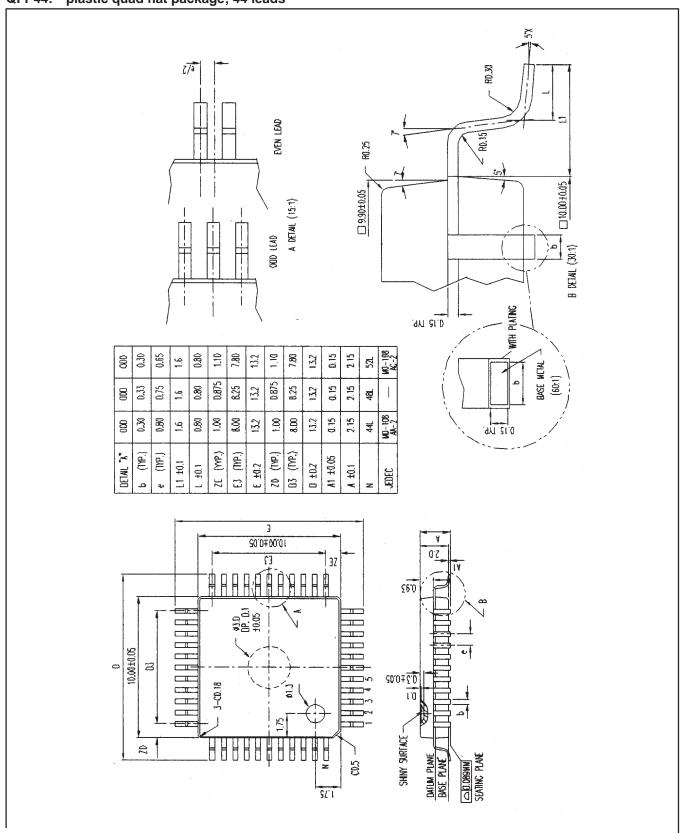
UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	e <sub>1</sub>	L	ME	Мн	w	Z <sup>(1)</sup> max.
mm	4.7	0.51	4.0	1.70 1.14	0.53 0.38	0.36 0.23	52.50 51.50	14.1 13.7	2.54	15.24	3.60 3.05	15.80 15.24	17.42 15.90	0.254	2.25
inches	0.19	0.020	0.16	0.067 0.045	0.021 0.015	0.014 0.009	2.067 2.028	0.56 0.54	0.10	0.60	0.14 0.12	0.62 0.60	0.69 0.63	0.01	0.089

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT129-1	051G08	MO-015AJ			<del>92-11-17</del> 95-01-14



QFP44: plastic quad flat package; 44 leads



Philips Semiconductors Product specification

## 80C51 8-bit microcontroller family 4K/8K/16K/32K Flash

### 89C51/89C52/89C54/89C58

#### Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

<sup>[1]</sup> Please consult the most recently issued datasheet before initiating or completing a design.

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**Short-form specification** — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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